

**AMENDMENTS TO THE CLAIMS**

**Listing of claims:**

This listing of claims replaces all prior versions and listings of claims in the application.

1. (Original) A manufacturing method of a multilayer wiring board, comprising: a first step of mounting an electronic component on a frame resin layer including at least one of glass cloth, filler and nonwoven fabric, said frame resin layer including no electronic component therein; and a second step of forming a resin layer by placing a semi-cured resin sheet on said frame resin layer so as to contact the mounted electronic component, and completely curing said semi-cured resin sheet with the electronic component buried therein.

2. (Original) The manufacturing method as claimed in claim 1, wherein the semi-cured resin sheet includes fragments of at least one of filler and nonwoven fabric.

3. (Withdrawn) A manufacturing method of a multilayer wiring board, wherein: said multilayer wiring board is manufactured as successively testing an incomplete multilayer wiring board using a test apparatus used for evaluating the multilayer wiring board; and said test apparatus comprises: a probe part configured to be connected to said incomplete multilayer wiring board in a half finished state before completion; and a supplementary part supplementing an element of the multilayer wiring board, said incomplete multilayer wiring board lacking said element.

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4. (Withdrawn) The manufacturing method as claimed in claim 3, wherein the supplementary part includes layer wiring of the multilayer wiring board, said incomplete multilayer wiring board lacking said layer wiring.

5. (New) The manufacturing method as claimed in claim 1, further comprising a third step of forming wiring patterns on the cured resin layer.